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(71)Applicant : NGK SPARK PLUG CO LTD
 (72)Inventor : KODERA EIJI
 HOTTA YASUTAKE
 OGAWA KOJU

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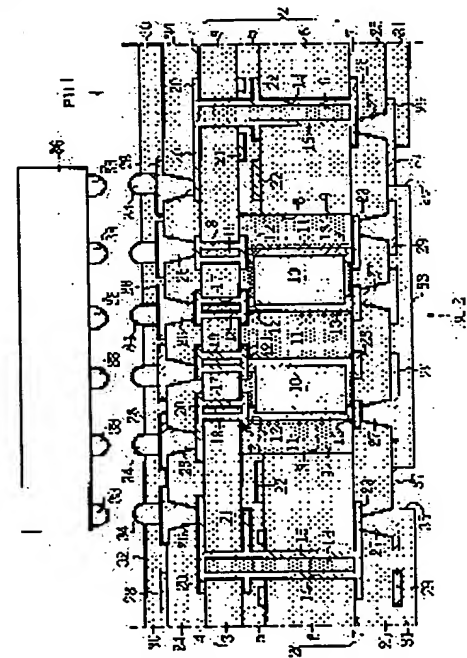
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(54) WIRING SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a wiring substrate, in which adhesion between an electronic component to be embedded and embedding resin therefor is enhanced and connections between the electronic component and an internal wiring layer or an IC chip mounted on a first surface is made sure and stable, and to provide a method of manufacturing the wiring substrate.

SOLUTION: The wiring substrate 1 contains an insulation substrate 2, having a front surface 4 and a back surface 7; a depression 8 having an opening on the back surface 7 of the insulating substrate 2, and an electronic component 10, the surface of which has been coated in advance with an organic compound 11, composed of titanium base, aluminum base, silane base, or a mixture of these, and which is embedded in the depression 8 via a resin 9.



LEGAL STATUS

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